

LEENO



DISCLAIMER

All Information about our company's financial outcome in this material were written by Korean International Financial Reporting Standards.

In addition, This material includes information about the future predictions which can be affected by known or unknown risks and uncertainties.

The Future business prospect is supposed to be check. Because, Many such factors such as market situation and business strategy will be important in determining our future results.

Up-to-date our company information is notified in our website. (https://leeno.com)

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I. Business Description

01. About 'LEENO'

Company Name	Leeno Industrial Inc.		
CEO	Chae-Yoon, Lee		
Foundation	NOV 1978 (Incorporated in DEC 1996)		
Business Category	Manufacture Semiconductor Test Probe and Socket		
Capital Stock	(KRW) 7.62 Billion won (`23)	(KRW) 7.62 Billion won (`24.1Q)	
Revenue	(KRW) 255.6 Billion won (`23)	(KRW) 54.9 Billion won ('24.1Q)	
Number of Employees	639 persons (`23)	639 persons ('24.1Q)	
Head Office Location	10, MIEUMSANDAN-RO 105BEON-GIL, GANGSEO-GU, BUSAN, KOREA		
Homepage	https://leeno.com		

[MAIN HISTORY]

2001.12 Listed on KOSDAQ(058470)

2003.10 Appointed "Prospective Exporter, Small&Medium Business"

2004.12 Certified by DAS for ISO 9001

2004.11 Received an award from Korean prime minister for excellence in regional innovation

2005.09 Appointed "Excellent Business" and awarded Korea Productivity Award

2005.11 Awarded "10 Million Dollar Export Achievement Award"

2006.11 Certified by DAS for ISO 14001

2007.01 Appointed "Technology Innovative Small and Medium Enterprise"

2007.07 Awarded "Grand Prize of Small and Medium Business people In Busan"

2010.01 Concluding a contract to supply the probe for supersonic to Siemens

2010.11 Awarded "20 Million Dollar Export Achievement Award"

2012.01 Certified ISO13485

2013.05 Voted World Class 300

2013.06 Bonus Issue

2013.08 Moved in to New extend Head office

2013.12 Awarded "30 Million Dollar Export Achievement Award"

2014.03 Awarded "Tin Tower Order of Industrial Service Merit"

2016.03 Awarded Citation in 'Taxpayer day'

2016.12 Awarded "50 Million Dollar Export Achievement Award"

2017.12 Awarded "70 Million Dollar Export Achievement Award"

2020.02 Completed "NOKSAN Factory" for Medical and Plating part.

2021.12 Awarded "100 Million Dollar Export Achievement Award"

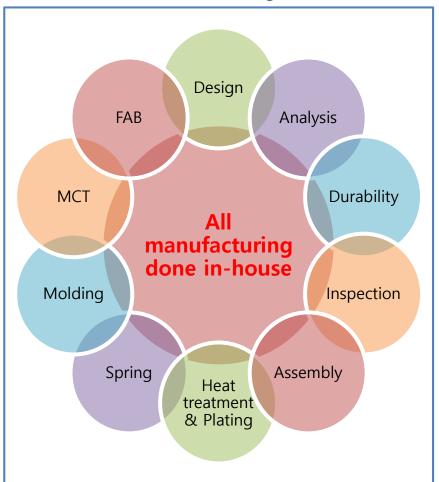
2022.12 Awarded "200 Million Dollar Export Achievement Award"

2023.12 Certified ISO45001



02. Competitiveness

World Class Manufacturing



Consistent, Quality Products



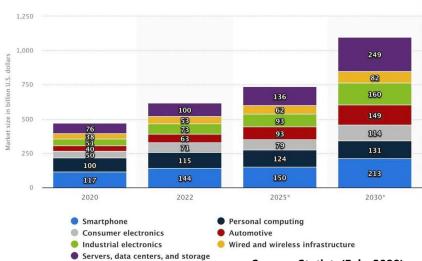








■ Semiconductor market size worldwide from 2020 to 2030, by application (units: billion U.S. dollars)



Source: Statista(Feb, 2023)

Semiconductor market size worldwide by application will total 1,098 billion dollars in 2030, according to Statista. In addition, smartphone(213 billion dollars), Servers & data centers & storage(249 billion dollars), Personal computing(131 billion dollars), Automotive(149 billion dollars), Industrial electronics(160 billion dollars), Consumer electronics(114 billion dollars) and Wired & wireless infrastructure(82 billion dollars) is expected to growth in 2030.

According to Current Trend and The Fourth Industrial Revolution(such as lot, AI, 5G, VR, AR, Big-data, Metaverse, Automatic Driving & Electronic Car), As types and functions of non-memory and memory semiconductors go into The Devices is diversifying, Demands for functions and characteristics in Semiconductor testing market is increasing. LEENO will be accompanied by the growth of the new IT market, to actively participate in the needs of the semiconductor test market with LEENO PIN and IC TEST SOCKET.

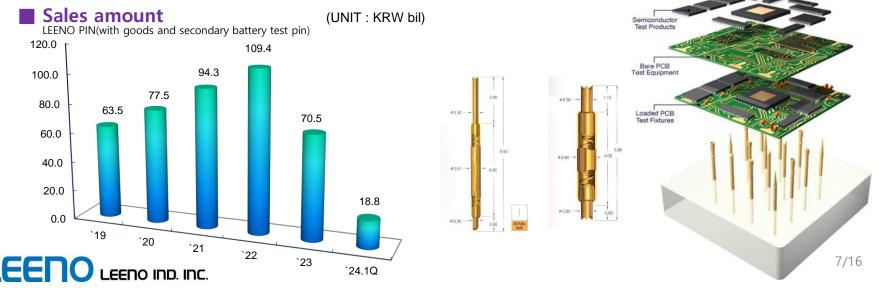


II. OUR PRODUCTS

01. LEENO PIN

- Contact with electronic equipment and PCB circuit to check whether properly to make or not
- LEENO PIN is our own-brand as test probe pin, and about 990 companies (Based on sales of 2023) are using 'LEENO PIN'

 Recently, Along with high demand of Fine Pitch Probe with variety of electronic equipment, we are satisfied our customer's needs providing high quality and competitive pricing.

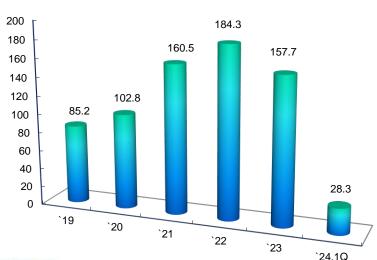


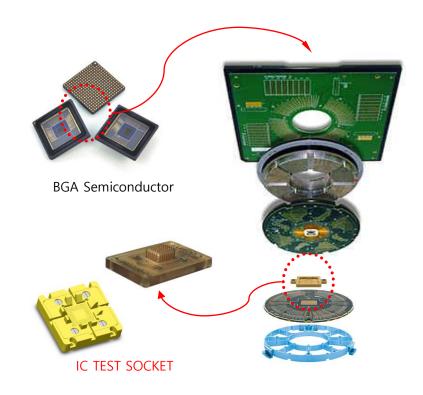
- IC Test socket has been used to test memory and non-memory IC semiconductor. The purpose of this is to test electrical signal after contacting package which is located in test socket.
- Our <u>innovative vertical type in IC test socket</u> has been commercialized for 20 years through out developing innovative technology

Sales amount

IC TEST SOCKET(with probe card)

(UNIT: KRW bil)

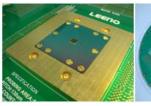


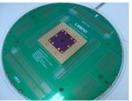




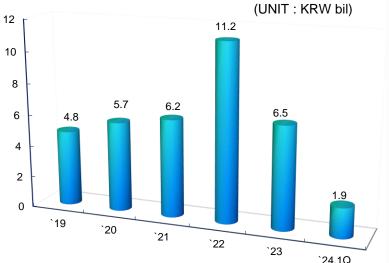
- The whole process semiconductor inspection equipment to test electrical characteristics in separated chips in wafer.
- LEENO is the best leading technology company to provide solution in competitive accelerating and evolved test market.
 - Long life Cycle
 - Quick Delivery
 - High Speed
 - Low Cost







Sales amount







- The demand for <u>secondary batteries to be used for key items in the IT sector</u> such as portable products is expected to increase more compared with the previous year.
- LEENO manufacture high-current test pin for hybrid car to cope with active market.
- World-class technology and pin production experience in domestic market make possible for the final customer to use secondary battery safely.





- 25th Jan, 2010 LEENO Industrial Inc. makes an agreement about supplying Ultrasonic wave probe component with SIEMENS
 - What is the 'Ultrasonic wave probe'?: It is single unit machine of ultrasonic diagnostic imaging device which has function to generate and detect ultrasonic wave and contacted directly with human body.
 - (X Regarded as a consumable parts in ultrasonic wave diagnostic device)
- This will be a base for <u>new growth</u> of LEENO's new market
- Manufacture the <u>core part of probe</u>, developing high value



_ens

 This part is contacted with human body directly and control ultrasonic wave's direction.

Shield

•To remove noise from ultrasonic wave prove and for electrical grounding and shielding role.

Matching Layer

• To control and magnify ultrasonic wave's direction in the ultrasonic wave probe.

Flexible PCB

• The component for applied and received voltage.

Backe

 This part absorbs the backside direction's ultrasonic wave which was generated from ultrasonic wave probe.

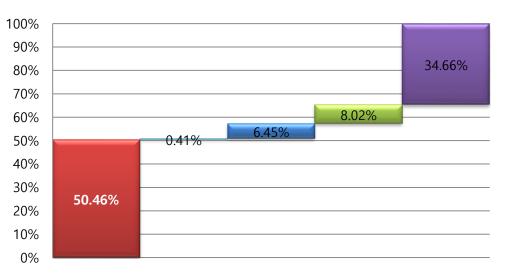


III. Financial Highlight

01. Stock Information

 LEENO is doing our best to enhance the company's value in return for your trust and encouragement.

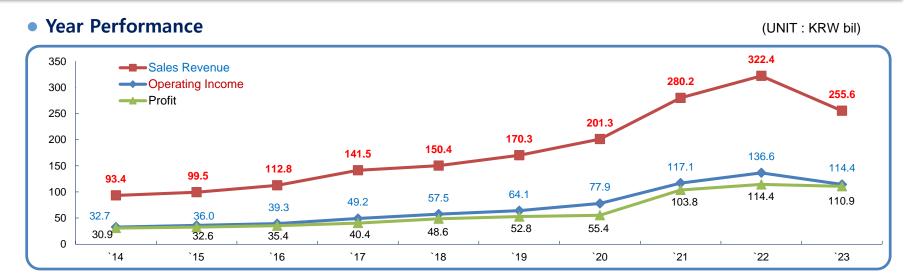


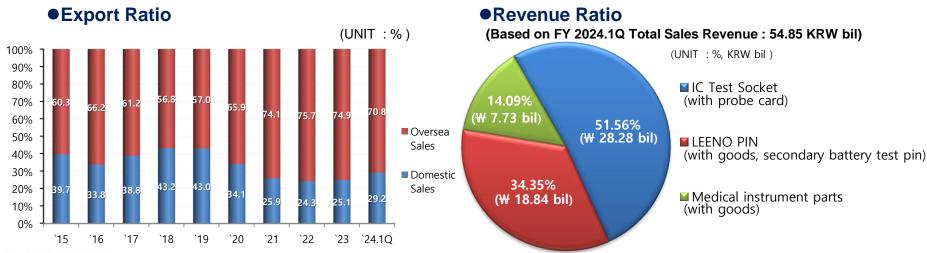


- CEO(CHAE-YOON,LEE) 5,283,669 (34.66%)
- Wasatch Advisors 1,223,169 (8.02%)
- ■National Pension Service 982,494주(6.45%)
- Treasury stock 63,250 (0.41%)
- Other 7,689,788 (50.46%)

- ➤ Based on Stockholding status Report by National Pension Service(At AUG 7TH, 2023), Wasatch Advisors, Inc (At JAN 10th, 2024)
- > According to Treasury stock, Please find the Disclosure of Treasury stock at NOV 29th, 2019.







03. Dividend

• **Dividend** (UNIT : KRW)

Date	Par value	Net income	Earning Per Share (EPS)	Dividend	Dividend yield ratio(%)	Total Dividend amount
`23	500	110,923,015,440	7,308	3,000	1.48	45,537,360,000
`22	500	114,363,791,327	7,534	3,000	1.85	45,537,360,000
`21	500	103,805,815,149	6,839	2,500	1.26	37,947,800,000
`20	500	55,378,772,170	3,648	1,500	1.14	22,768,680,000
`19	500	52,790,182,377	3,485	1,200	1.87	18,214,944,000

➤ About the Dividend in 2019~2023, Total Dividend amount for 15,179,220 stocks except Treasury stocks(63,250).

Stable Management

- Superior Financial structure and cashable property
- No-borrow Management & Maintenance
- Increasing of operating profit & Net income
- Maintenance of profit from high added value



Policy for Stockholders



04. Financial Statement

(UNIT: KRW)

Balance Sheet

Statement of comprehensive income (Accumulated)

(UNIT: KRW)

	FY 2024.1Q	FY 2023
I . Current Assets	393,977,738,842	372,372,898,847
П. Non-Current Assets	212,921,270,685	210,496,566,447
Total Assets	606,899,009,527	582,869,465,294
I . Current Liabilities	71,946,883,237	23,110,842,940
П. Non-current Liabilities	2,762,303,332	2,684,424,288
Total Liabilities	74,709,186,569	25,795,267,228
I . Issued capital	7,621,185,000	7,621,185,000
П. Capital Surplus	5,601,810,444	5,601,810,444
Ⅲ. Other Capital Adjustments	(2,353,516,350)	(2,353,516,350)
IV. Retained Earnings	521,320,343,864	546,204,718,972
Total Equities	532,189,822,958	557,074,198,066
Total Equities and Liabilities	606,899,009,527	582,869,465,294

	FY 2024.1Q	FY 2023.1Q	FY 2023
I . Revenue (Sales)	54,852,145,711	49,091,082,613	255,573,034,656
Ⅱ. Cost of sales	28,530,350,532	29,656,943,304	127,238,409,519
Ⅲ. Gross Profit	26,321,795,179	19,434,139,309	128,334,625,137
IV. Selling General Administrative Expenses	3,019,643,001	2,171,569,889	13,956,224,846
V. Operating Income	23,302,152,178	17,262,569,420	114,378,400,291
VI. Non-operating Income	3,642,474,133	3,025,315,419	27,865,067,804
VII. Profit before tax	26,944,626,311	20,287,884,839	142,243,468,095
VIII. Income tax expense	6,342,026,685	4,558,563,877	31,320,452,655
IX. Profit	20,602,599,626	15,729,320,962	110,923,015,440
X. Other comprehensive Income	50,385,266	12,958,710	(1,495,040,200)
XI . Total comprehensive Income	20,652,984,892	15,742,279,672	109,427,975,240
XII. Basic Earnings per share	1,357	1,036	7,308



APPENDIX





